



Product Change Notification

Change Notification #: 115248 - 00

**Change Title: Intel® Server Chassis
H2312XXLR2,
PCN 115248-00,
Transport Media,
Packing Material Change**

Date of Publication: January 09, 2017

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	January 19, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is changing the internal packaging material on the Intel® Server Chassis H2312XXLR2 from cardboard to foam for better content protection. Please refer to the pictures below for the details of the change.

Please refer to the Products Affected table below for a summary of TA changes.



Figure 1. Before change



Figure 2. After change

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Post Change TA
H2312XXLR2	942352	J17277-001	J17277-002

PCN Revision History:

Date of Revision:
January 09, 2017

Revision Number:
00

Reason:
Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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